2012 International Semiconductor Conference Dresden - Grenoble (ISCDG)

alternating venue in Dresden (Germany) and Grenoble (France) every other year

Technology, Design, Packaging, Simulation and Test
International Conference, Short Course and Table Top Exhibition

September 24 to 26, 2012 - MINATEC Campus, Grenoble, France

Grenoble and Dresden are the two major European Semiconductor Research, Development and Production sites. In the preceeding editions of 2009 and 2011, the conference was named "Semiconductor Conference Dresden". The objective of the ISCDG is to enhance the visibility of both cities international excellence. The 2012 ISCDG will be held in Grenoble for the first time. The venue will be alternating in Grenoble and Dresden every other year.

Main areas covered by the conference: Materials, devices and systems science, engineering and architectures and their characterization available soon

Papers are requested in the following areas:

- **Integrated Circuit and System Design**
  Mixed-signal, analogue and digital circuits and systems for high speed and/or low power consumption, adaptive power management, RF up to sub-THz, low costs, and advanced performance and density, circuits in More than Moore and Beyond Moore technologies. Manufacturing challenges (cost and cycle time reduction, test, wafer - prime - production etc..)
- **More Moore and Beyond Moore Devices Technologies and Architectures**
  Ultimate CMOS (silicon and IV-IV strained alloys on insulator, multi-gate and channels transistors, III-V channels), nanowires; Thin films dielectrics: Hik and Low K; nano-materials; Beyond Moore: TunFETs, carbon electronics,…
- **Memory technologies**
  Sand alone and Embedded MemoryTechnologies, New memory technologies: RRAMs, CBRAMs, MRAMs, 1T DRAM, …
- **More than Moore technologies**
  MEMS, NEMS, power devices (GaN, GaP), RF and analog passive components (MIM, filters, supercapacitors, inductances,…); Spintronics based devices; Bio sensors, Imagers, thermoelectric, energy harvesting…
- **Interconnection and Packaging Technologies**
  3-D and novel interconnects, Wire bonding, flip chip, solder replacement flip chip, under bump metallurgy, high density substrates, New packaging technologies for single chip, multi-chip, wafer level, power and stacked-die packages, Wafer bumping and thinning, …
- **Optical Devices and Photonics**
  Optical component assemblies, electro-optical modules, waveguides, silicon based photonic devices, organic devices, optical materials
- **Organic and flexible electronics**
  polymer and organic, ink-jet printed electronics, organic PV and PV in organic, OLEDs, …
- **Characterization, Quality and Reliability**
  Electrical characterization, testing strategies and protocols, physical characterization for process development and process control. Component, board and system level reliability assessment, failure analysis, interfacial adhesion, accelerated testing and models, component and system qualification.
- **Modeling and Simulation**
  EDA, TCAD, electrical, thermal, thermo-mechanical, reliability, optical, modeling and simulation for devices, component and system level applications.

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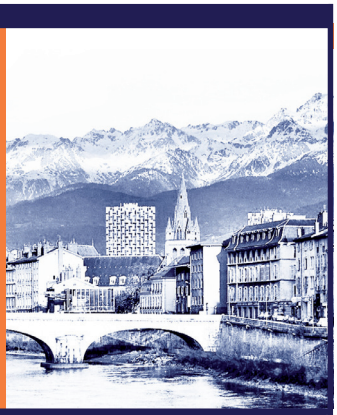

Key Dates:

Paper submission deadline	**April 30, 2012**
Paper acceptance	**June 1, 2012**
Deadline for early bird registration (accomodation, conference and short course fees)	**August 15, 2012**

Submit Paper

Submission of papers in the areas mentioned above are encouraged and solicited to describe original work.

The paper must include the purpose, applications, results, comparison with the state-of-the-art, conclusions, visualizing pictures and key references.

All conference papers will be included in IEEEXplore.

Papers will be presented at the conference as talks or posters.

» Please send your proposal to paper-scd@gerotron.com

Guidelines for submitted papers:

- Papers have to be formatted in accordance with the IEEE – Manuscript Templates for Conference Proceedings
- Contributions can only be accepted in English language
- Paper length: 3-4 pages, paginated with Arabic numerals at bottom right
- File format: pdf, file size max. 5 MB

In addition we need the following information:

Please fill out the form below and send this document together with your paper submission to us.

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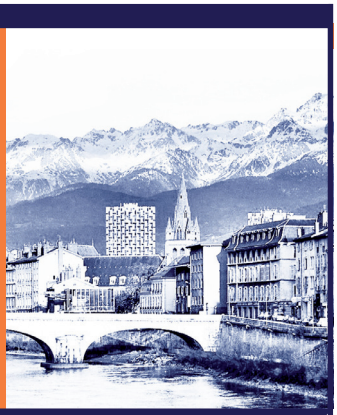

Please return form to fax no. + 49 89 857 76 05 till August 15, 2011

Registration Form / Sponsoring opportunities for Table-Top Exhibition

☐ We want to register as exhibitor for Semiconductor Conference Dresden 2011

Floor space (booth: Table and two chairs, incl. catering for two persons) 2.800 Euro + 19% VAT

☐ We will bring along our own display wall.

☐ We would like to hold a 60-90 minutes lecture

Topic: _____

☐ We would like to give a 20-minutes-booth presentation

Topic: _____

☐ We are interested to appear on the SCD 2011 as sponsor for:

☐ Writing pads and pencils	☐ Lanyard cords	☐ Delegate bags
☐ Coffee breaks Tuesday	☐ Coffee breaks Wednesday	☐ Lunch Tuesday
☐ Lunch Wednesday	☐ Advertisement on display wall	☐ _____

☐ We want to place an advertisement:

☐ In the exhibition catalogue (4-coloured, circulation 500 pcs.)

☐ 88 x 95 mm (1/2 page):	180,00 Euro + 19% VAT
☐ 88 x 200 mm (1/1 page):	300,00 Euro + 19% VAT
☐ Outside back cover (88 x 200 mm)	500,00 Euro + 19% VAT

☐ Logo on the website with link: 500,00 Euro + 19% VAT

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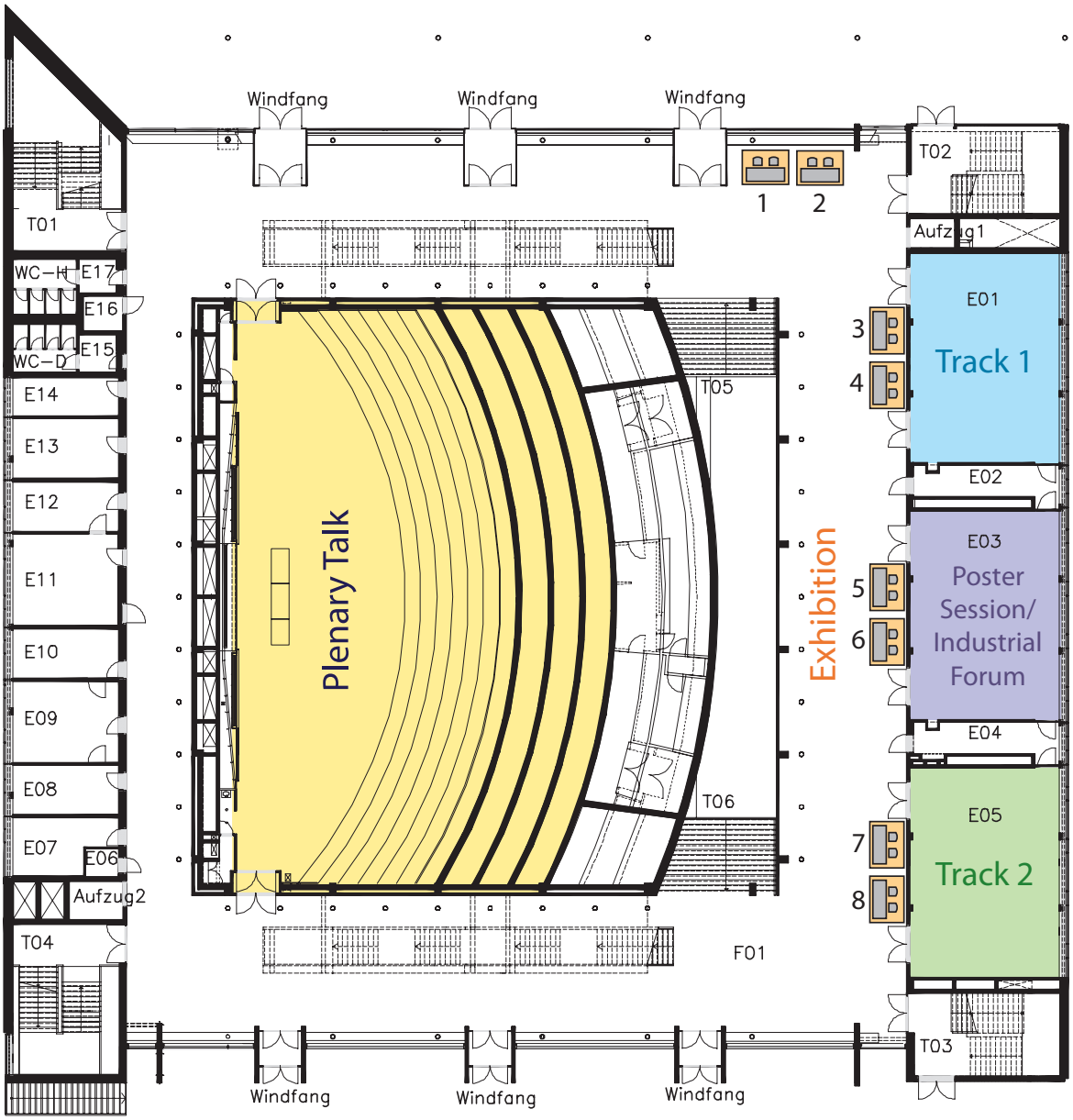
Floor Plan



Booth: Table and two chairs

Changes can be made until further notice

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